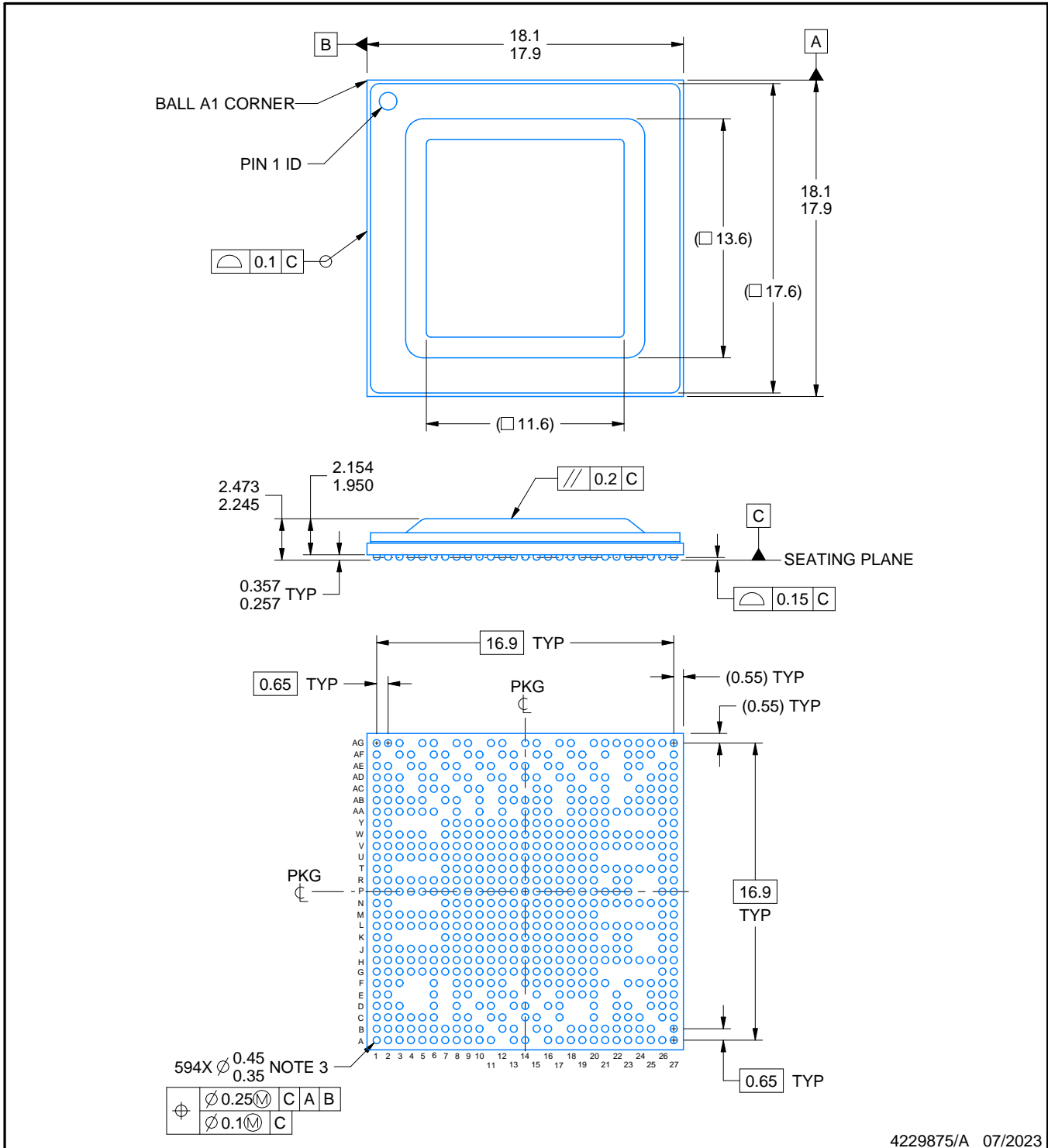


PACKAGE OUTLINE

AMW0594A

FCBGA - 2.473 mm max height

BALL GRID ARRAY



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NOTES:

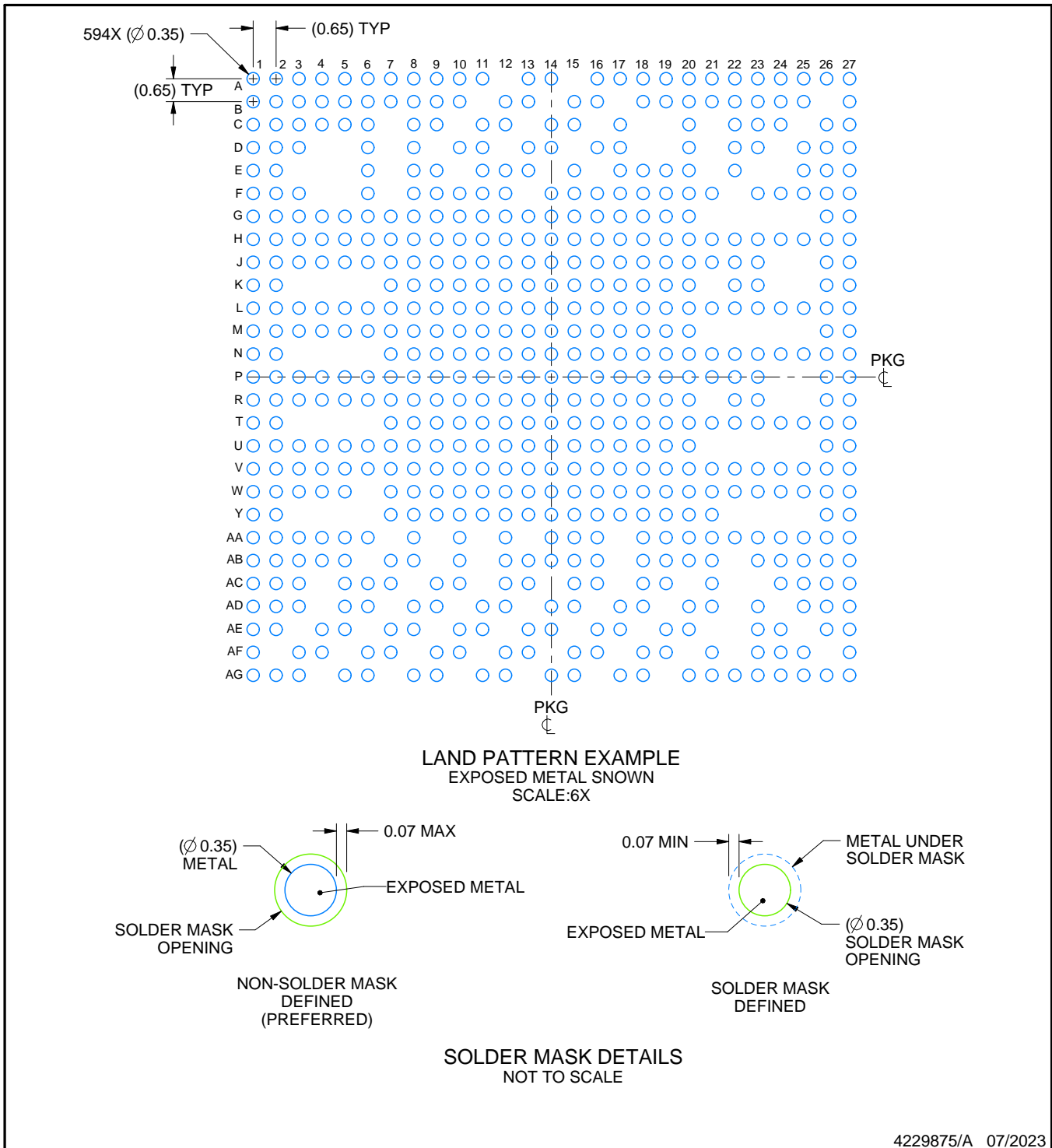
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- Ball diameter after reflow. Dimension is measured at the maximum solder ball diameter parallel to primary datum C.

EXAMPLE BOARD LAYOUT

AMW0594A

FCBGA - 2.473 mm max height

BALL GRID ARRAY



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NOTES: (continued)

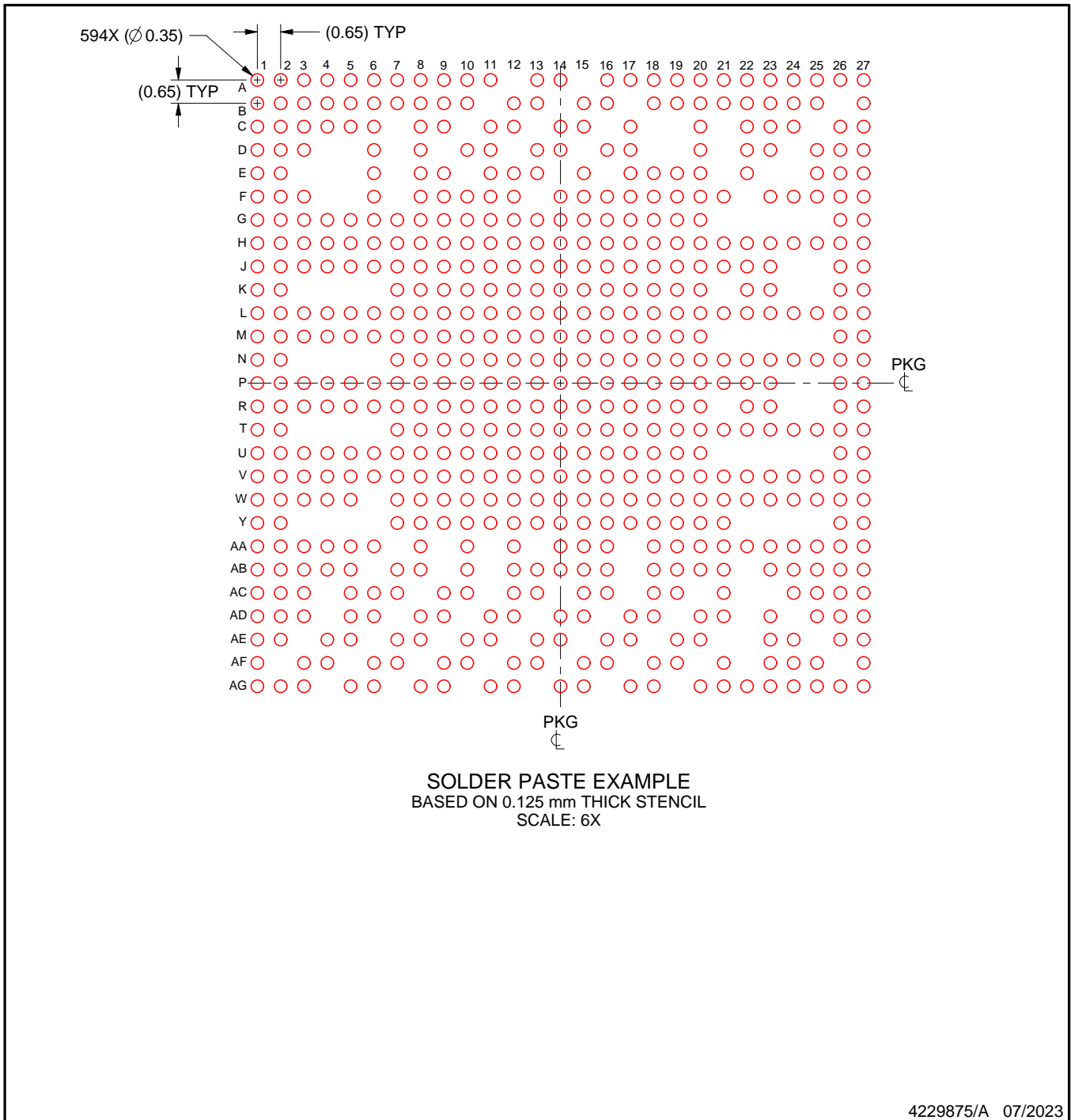
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).

EXAMPLE STENCIL DESIGN

AMW0594A

FCBGA - 2.473 mm max height

BALL GRID ARRAY



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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